

Company News

Meet Our New President and Chief Operating Officer: David Fromm

David Fromm was recently named president and COO of QP Technologies and Promex Industries. This expands on his previous role as Promex COO, in which he oversaw the development of advanced microelectronics manufacturing processes and built strong customer partnerships. In his role as president, Dave succeeds Dick Otte, who remains CEO of both companies.

Dave holds a Ph.D. in physical chemistry and a B.A. in biochemistry. Throughout his career, he has driven scientific innovation through research and patented technologies, including multiple patents in molecular diagnostics systems and high-speed atomic force microscopy. His technical expertise and proven leadership will be instrumental to both companies' growth as we continue to expand our onshore packaging and assembly capabilities.

[Read our press release](#) to learn more about Dave's new role.



Technology Bites

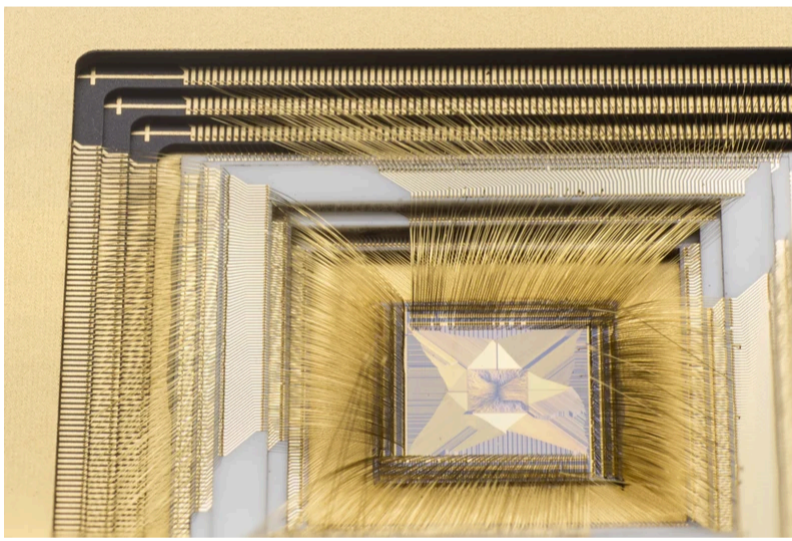
Packaging: The Make-or-Break Factor in mmWave Performance

Wireless connectivity and satellites, long-term reliability, signal integrity and thermal performance are essential features for electronics that power high-speed, high-capacity RF applications such as military-aerospace. These devices increasingly operate at the millimeter-wave (mmWave) level, which means they require precise packaging to maintain high performance.

However, RF devices are extremely sensitive and vulnerable to impedance mismatches, signal loss, heat dissipation, and other failures that can occur during packaging.

Our latest blog explores these challenges and their solutions to help you make the best decisions for your mmWave electronic designs.

[Read the blog](#) for more on mmWave packaging.



Upcoming Events (co-exhibiting with [Promex Industries](#))

- [IMS](#), Jun. 7-12
 - Thomas M. Menino Convention & Exhibition Center, Boston, MA
 - **Booth 24072**
- [iMAPS Symposium](#), Sept. 28-Oct. 1
 - Encore Boston Harbor, Boston, MA
 - **Booth 113**

**QP TECHNOLOGIES**
MICROELECTRONIC PACKAGING & ASSEMBLY SOLUTIONS